

1ZHP35AB17CHZ1Z4

- ◆Outline : 3.5*3.5*2.22mm
- ◆High efficiency
- ◆Good thermal dissipation & optical uniformity



Table of Contents:

Features-----	1
Product Code-----	2
Typical Product Characteristics-----	3
Maximum Rating-----	3
Dominant Wavelength Binning-----	4
Intensity binning-----	4
Forward Voltage Binning-----	4
Relative Spectral Power Distribution-----	5
Electronic-Optical Characteristics-----	5
Typical spatial distribution-----	5
Thermal Design for De-rating-----	6
Dimensions-----	6
Suggest Stencil Pattern-----	7
Packing-----	8
Reflow Profile-----	10
Precautions-----	11
Test items and results of reliability-----	14

Features

- RoHS2.0 and REACH-compliant
- MSL2 qualified according to J-STD 020
- ESD 8KV (HBM : MIL-STD-883 Class 3B)

Applications

- Portable lighting
- Outdoor lighting
- Indoor lighting
- Commercial lighting
- Industrial lighting
- Decorative lighting
- Agricultural lighting

■ **Product Code**

1 – Z – HP35 – A – B17C – H – Z – 1 – Z – 4

① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩

①	②	③	④	⑤
Process type	Category	Specification	Lens Angle code	Dice wavelength & Luminous rank
1: Normal process	Z: High Power LED	HP35: Ceramic 3535	A: 120°	BXXX: blue light & level

⑥	⑦	⑧	⑨	⑩
Support code	Zener & High CRI	Cap color code	Module & Lens code	Current code
H: HTCC	Z: Zener	1: Series No.	Z: Molding	4: 350mA

■ **Typical Product Characteristics(Ta=25°C)**

Luminous Flux (lm)			Dominant Wavelength (nm)	Forward Voltage (V) @350mA		Viewing Angle
Group	Min.	Max.		Min.	Max.	
B17	22	24	460-470	2.8	3.6	120°
B18	24	26				
B19	26	28				
B20	28	30				

Notes:

- Forward voltage (V_F) $\pm 0.05V$; Luminous flux (Φ_V) $\pm 7\%$; Wavelength (λ_d/λ_p) $\pm 1nm$; Viewing angle($2\theta_{1/2}$) $\pm 10^\circ$
- IS standard testing.



■ Maximum Rating (Ta : 25°C)

Characteristics	Symbol	Min.	Typical	Max.	Unit
DC Forward Current ¹	I _F			700	mA
Pulse Forward Current ²	I _{PF}			1000	mA
Reverse Voltage	V _R			5	V
Reverse Current	I _R			10	μA
Junction Temperature ³	T _j			150	°C
Storage Temperature Range	T _{stg}	-40	—	100	°C
Soldering Temperature	T _{sol}			250	°C

Notes:

1. For other ambient, limited setting of current will depend on de-rating curves.
2. D=0.01s duty 1/10.
3. When drive on maximum current , T_j must be kept below 150°C



■ Dominant Wavelength Binning

Bin code (350mA)	Min. λ_d (nm)	Max. λ_d (nm)
B460	460	465
B465	465	470

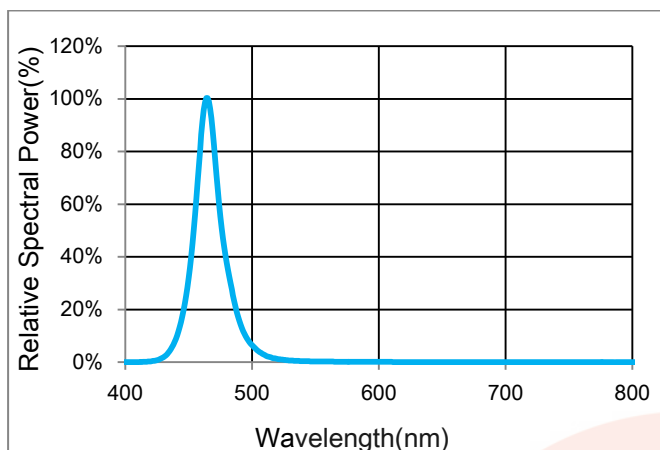
■ Intensity Binning

Bin code (350mA)	Min. Φ_v (lm)	Max. Φ_v (lm)
B17	22	24
B18	24	26
B19	26	28
B20	28	30

■ Forward Voltage Binning

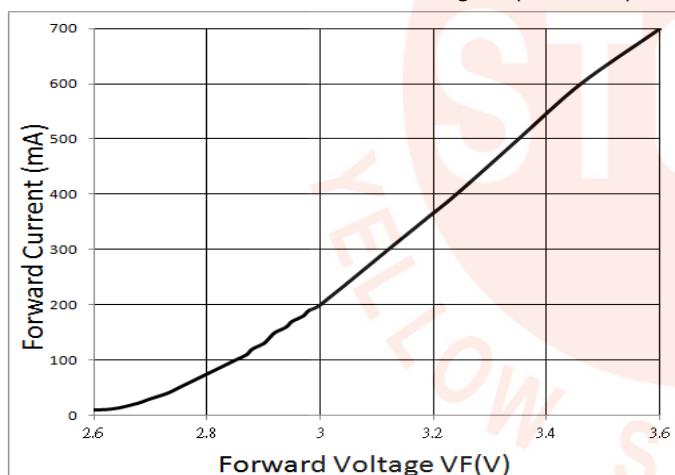
Bin code (350mA)	Min. V_F (V)	Max. V_F (V)
V2830	2.8	3.0
V3032	3.0	3.2
V3234	3.2	3.4
V3436	3.4	3.6

■ Relative Spectral Power Distribution

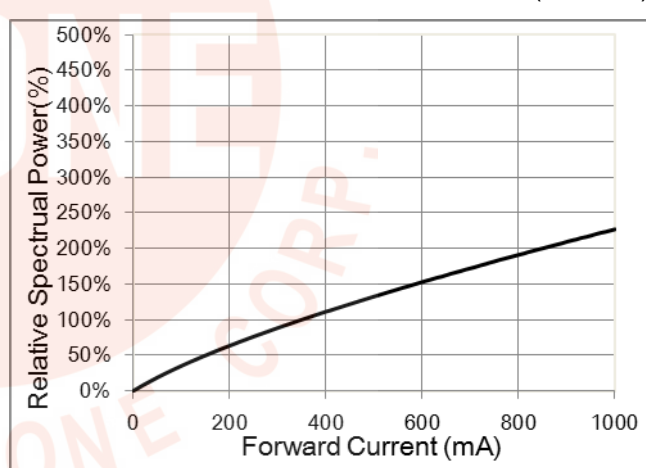


■ Electronic-Optical Characteristics

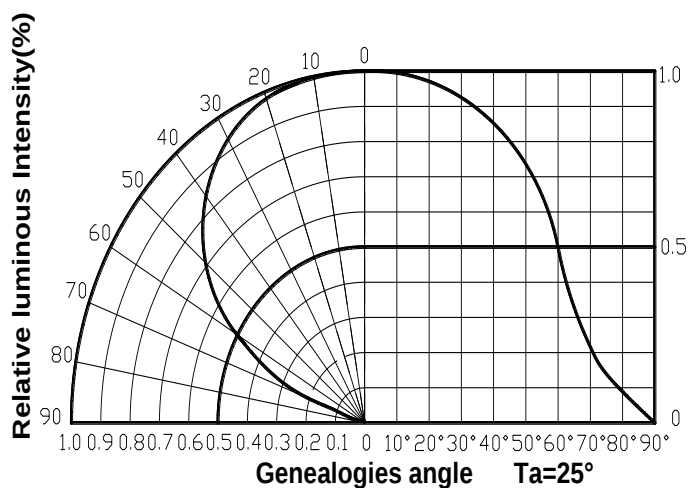
Forward Current vs. Forward Voltage ($T_a=25^\circ\text{C}$)



Relative luminous Flux vs. Forward Current ($T_a=25^\circ\text{C}$)

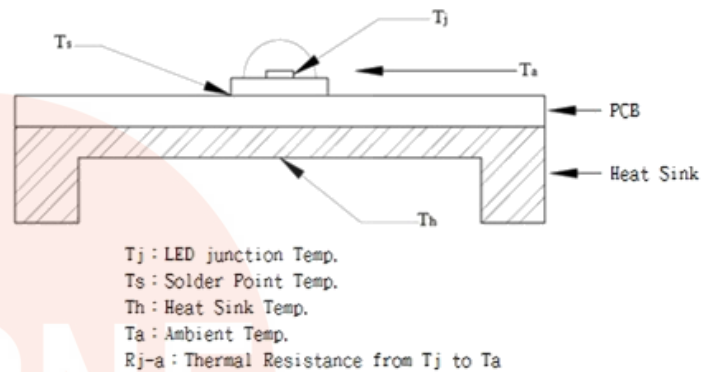
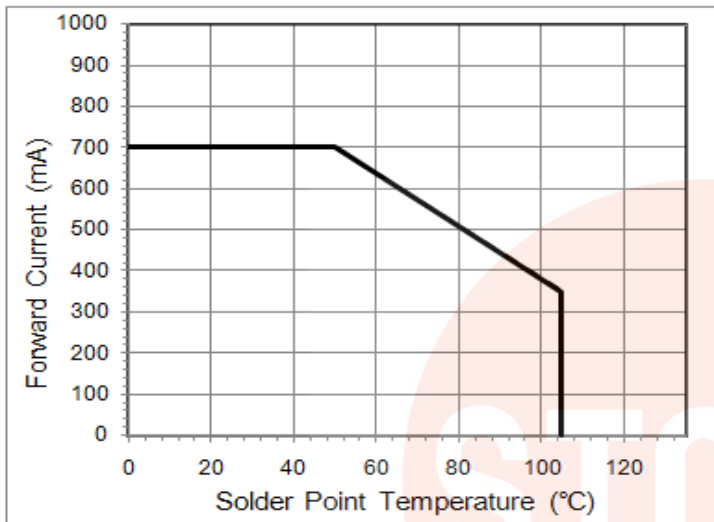


■ Typical Spatial Distribution

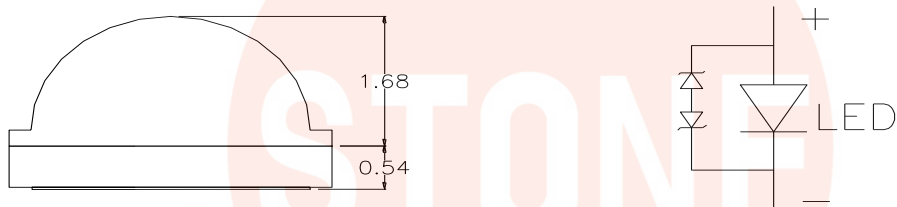
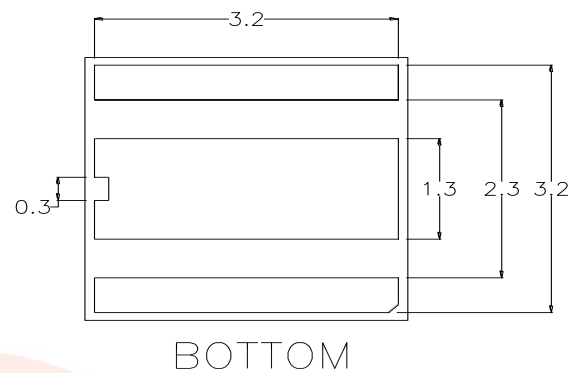
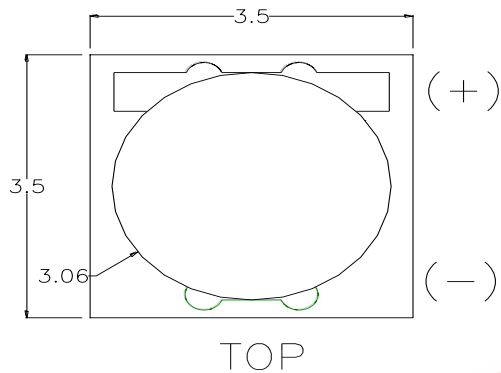


■ Thermal Design for De-rating

The maximum forward current is determined by the thermal resistance between the LED junction and ambient. It is crucial for the end product to be designed in a manner that minimizes the thermal resistance from the solder point to ambient in order to optimize lamp life and optical characteristics.



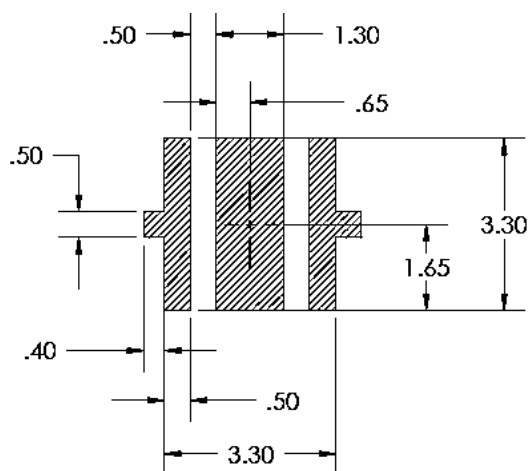
■ Dimensions



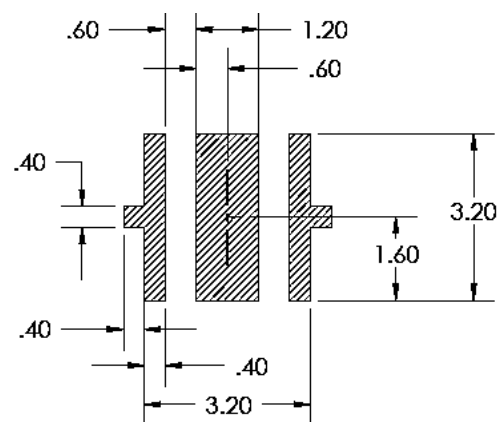
§ All dimensions are in millimeters.

§ Tolerance is $\pm 0.13\text{mm}$ unless other specified.

■ Suggest Stencil Pattern (Recommendations for reference)



RECOMMENDED PCB SOLDER PAD

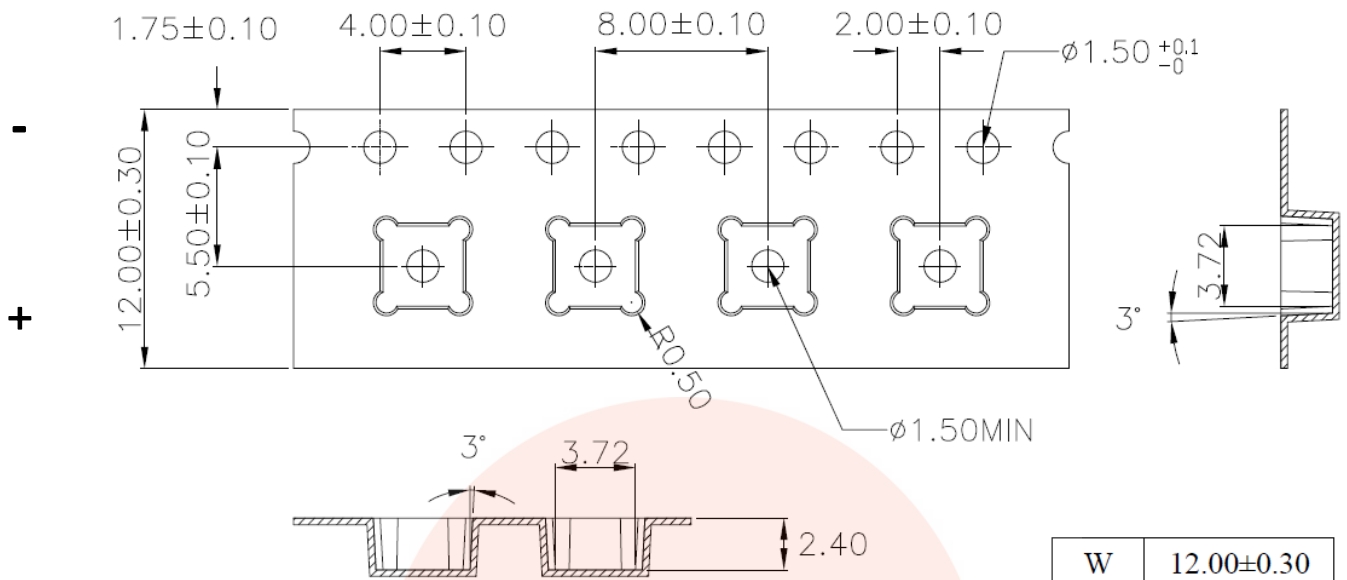


RECOMMENDED STENCIL PATTERN
(HATCHED AREA IS OPENING)

§ Suggest stencil $t = 0.12\text{ mm}$

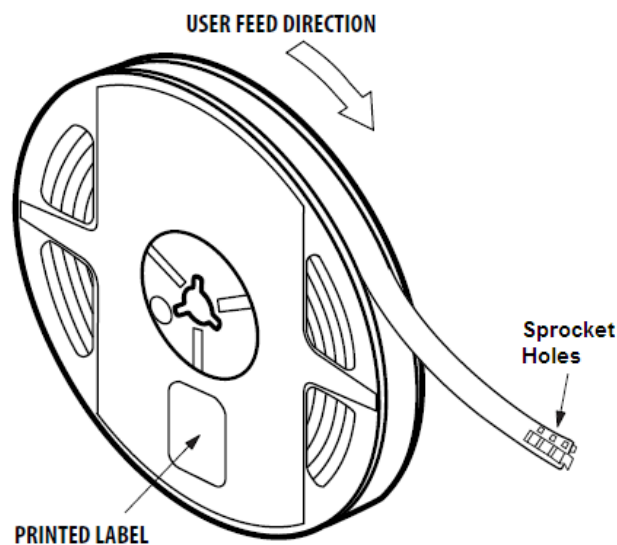
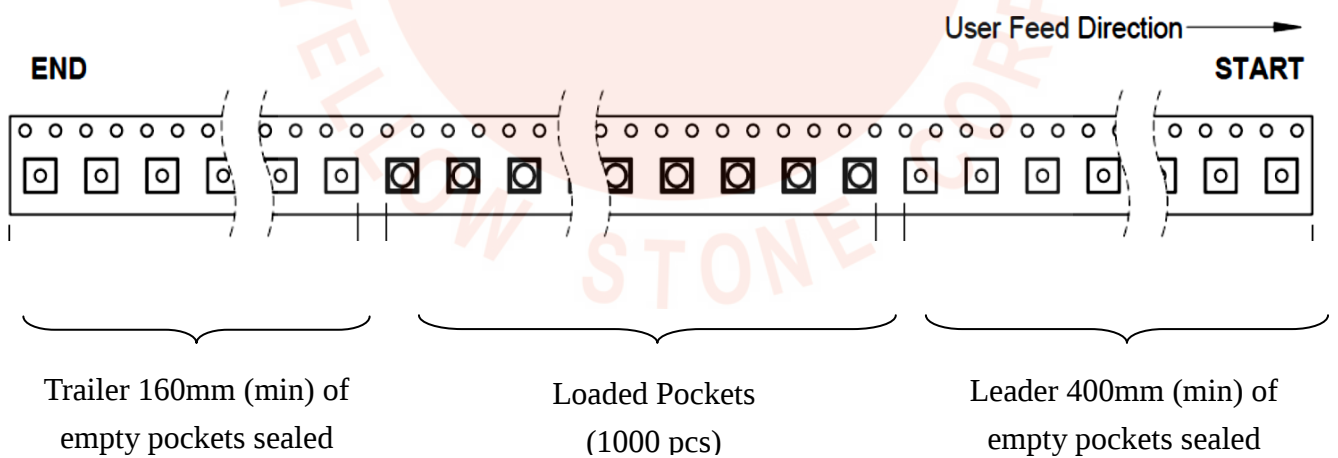
<http://www.ystone.com.tw>

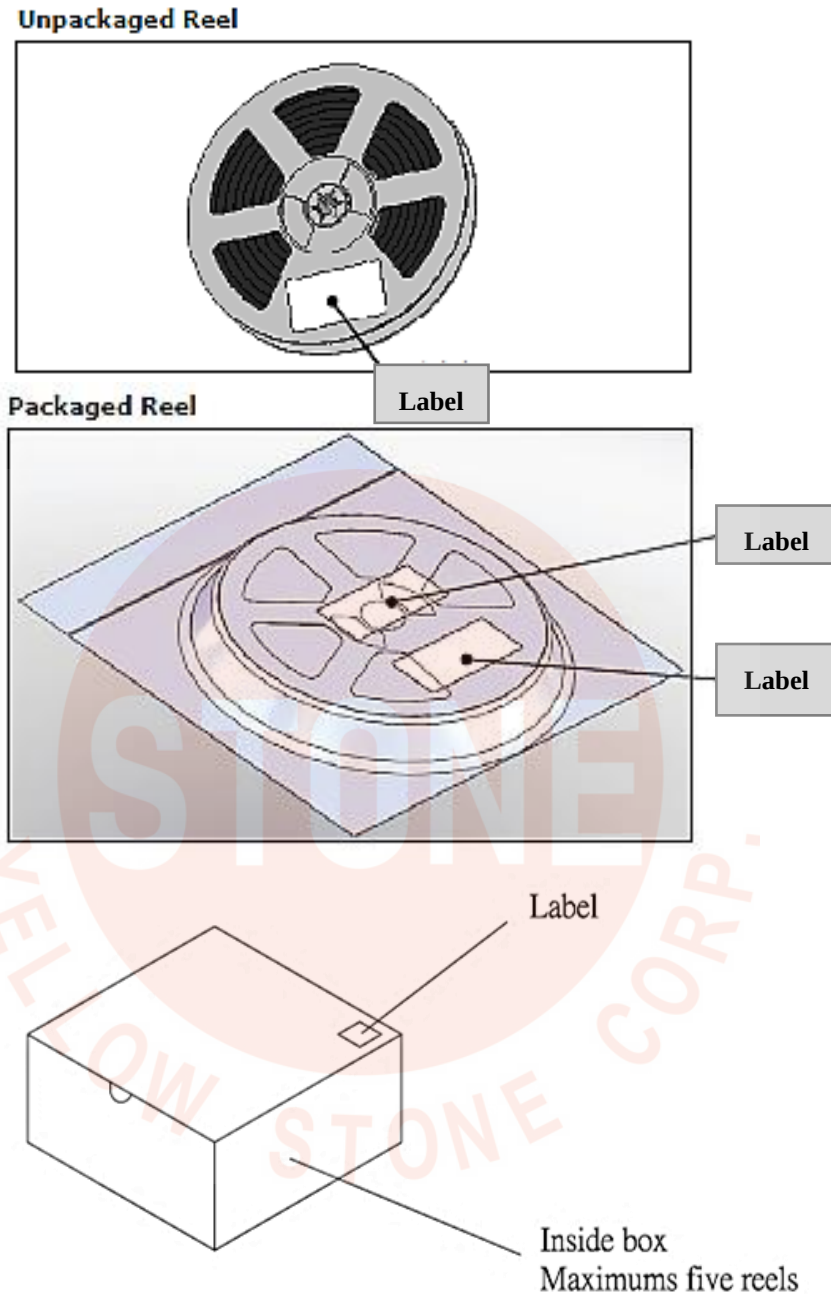
■ Packing



1. 10 sprocket hole pitch cumulative tolerance ± 0.20 .
2. Carrier camber is within 1 mm in 250 mm.
3. Material : Black Conductive Polystyrene Alloy.
4. All dimensions meet EIA-481-D requirements.
5. Thickness : 0.30 ± 0.05 mm.

W	12.00±0.30
A0	3.72±0.10
B0	3.72±0.10
K0	2.40±0.10



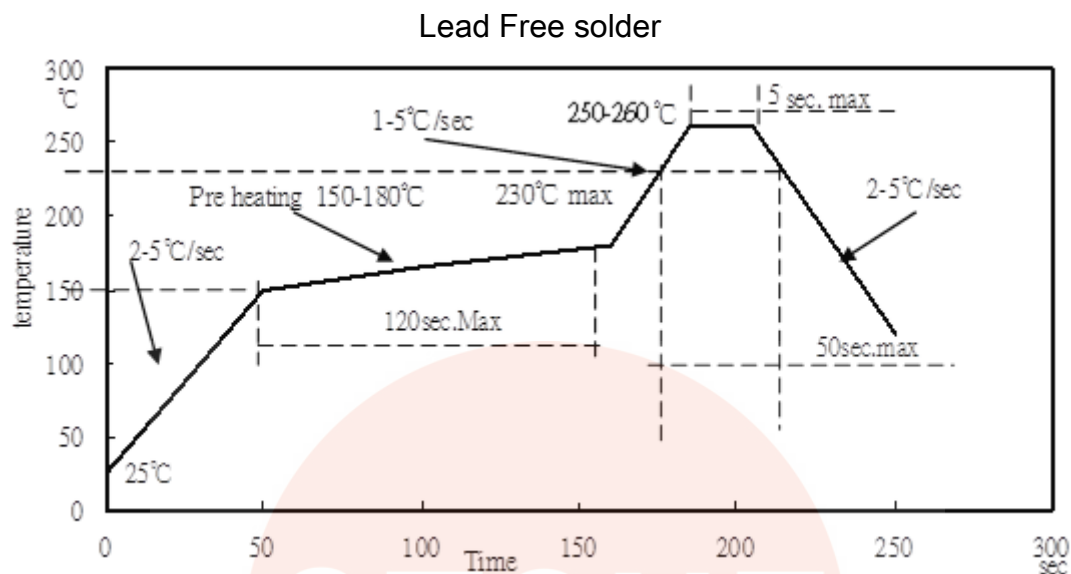


Notes:

1. Each reel (minimum number of pieces is 100 and maximum is 1000 for 120 degree product) is packed in a moisture-proof bag along with a packs of desiccant and a humidity indicator card.
2. A maximum of 5 moisture-proof bags are packed in an inner box (size: 260mm x 230mm x 100mm $\pm$ 5mm).
3. A maximum of 4 inner boxes are put in an outer box (size: 480mm x 275mm x 215mm $\pm$ 5mm).
4. Part No., Lot No., quantity should be indicated on the label of the moisture-proof bag and the cardboard box.

■ Reflow Profile

IR Reflow Soldering Profile



Notes:

1. The recommended reflow temperature is 240°C(±5°C). The maximum soldering temperature should be limited to 250-260°C.
2. Do not stress the silicone resin while it is exposed to high temperature.
3. The reflow process should not exceed 2 times.

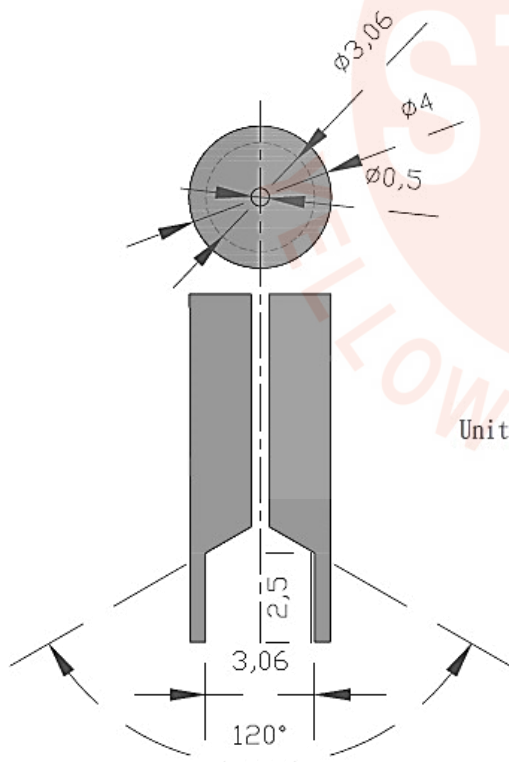
■ Precautions

1. Recommendation for using LEDs

- 1.1 The lens of LEDs should not be exposed to dust or debris. Excessive dust and debris may cause a drastic decrease in the luminosity.
- 1.2 Avoid mechanical stress on LED lens.
- 1.3 Do not touch the LED lens surface. It would affect the optical performance of the LED due to the LED lens' damage.
- 1.4 Pick & place tools are recommended for the remove of LEDs from the factory tape & reel packaging

2. Pick & place nozzle

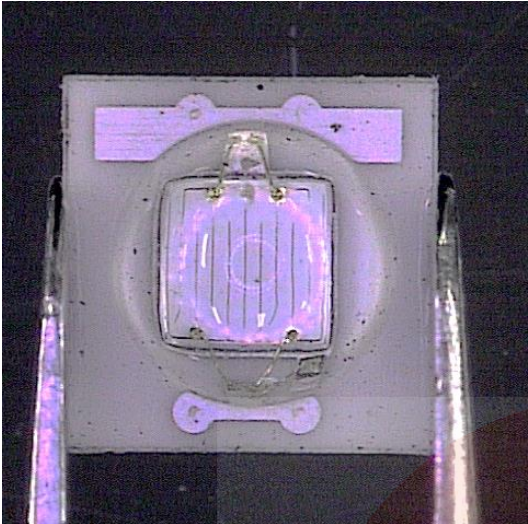
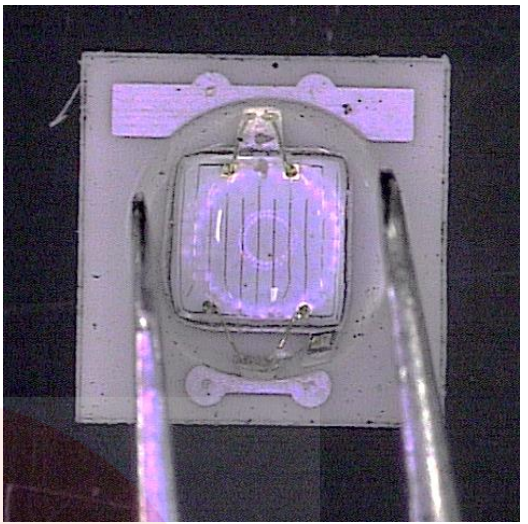
The pickup tool was recommended and shown as below



3. Lens handling

Please follow the guideline to pick LEDs.

- 3.1 Use tweezers to pick LEDs.
- 3.2 Do not touch the lens by using tweezers.
- 3.3 Do not touch lens with fingers.
- 3.4 Do not apply more than 4N (400gw) directly onto the lens.

Correct (√)	Wrong (X)
	

4. Lens cleaning

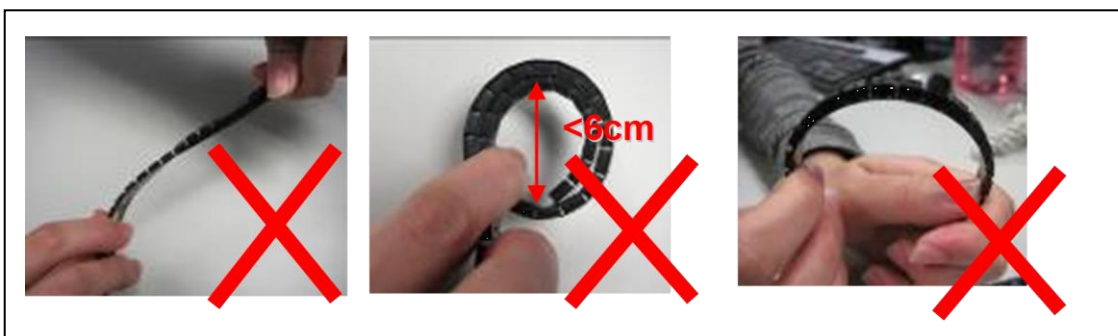
In the case which a small amount of dirt and dust particles remain on the lens surface, a suitable cleaning solution can be applied.

- 4.1 Try a gentle wiping with dust-free cloth.
- 4.2 If needed, use dust-free cloth and isopropyl alcohol to gently clean the dirt from the lens surface.
- 4.3 Do not use other solvents as they may directly react with the LED assembly.
- 4.4 Do not use ultrasonic cleaning which will damage the LEDs.

5. Carrier tape handling

The following items are recommended when handling the carrier tape of LEDs.

- 5.1 Do not twist the carrier tape.
- 5.2 The inward bending diameter should not be smaller than 6cm for each carrier tape.
- 5.3 Do not bend the tape outward.





6. Storage

6.1 The moisture-proof bag is sealed :

The LEDs should be stored at 30°C or less and 90%RH or less. And the LEDs are limited to use within one year, while the LEDs is packed in moisture-proof package with the desiccants inside.

6.2 The moisture-proof bag is opened :

The LEDs should be stored at 30°C or less and 60%RH or less. Moreover, the LEDs are limited to solder process within 168hrs. If the humidity indicator card shows the pink color in 10% even higher or exceed the storage limiting time since opened, that we recommended to baking LEDs at 60°C at least 24hrs. To seal the remainder LEDs return to the moisture-proof bag, it's recommended to be with workable desiccants.



■ Test Items and Results of Reliability

Test Item	Test Conditions	Duration/ Cycle	Number of Damage	Reference
Thermal Shock	-40°C 30min $\uparrow \downarrow$ 5min 125°C 30min	1000 cycles	0/77	AEC-Q101
High Temperature Storage	$T_a=100^{\circ}\text{C}$	1000 hrs	0/22	EIAJ ED-4701 200 201
Humidity Heat Storage	$T_a=85^{\circ}\text{C}$ RH=85%	1000 hrs	0/22	EIAJ ED-4701 100 103
Low Temperature Storage	$T_a=-40^{\circ}\text{C}$	1000 hrs	0/22	EIAJ ED-4701 200 202
Life Test	$T_a=25^{\circ}\text{C}$ $I_f=350\text{mA}$	1000 hrs	0/22	
High Humidity Heat Operation	85°C RH=85% $I_f=350\text{mA}$	1000 hrs	0/22	
High Temperature Operation	$T_a=85^{\circ}\text{C}$ $I_f=350\text{mA}$	1000 hrs	0/22	
ESD(HBM)	2KV at 1.5k Ω ;100pf	3 Times	0/22	MIL-STD-883

Failure Criteria				
Item	Symbol	Condition	Criteria for Judgment	
			Min	Max
Forward Voltage	V_F	$I_f=350\text{mA}$	-	$USL^1 \times 1.1$
Reverse Current	I_R	$V_R = 5\text{V}$	-	100 μA
Luminous Intensity	I_v	$I_f=350\text{mA}$	$LSL^2 \times 0.7$	-

Notes:

1. USL: Upper specification level
2. LSL: Lower specification level